



# Seagate® Nytro® XF1440

PCIe® Gen 3 x4 - NVMe SSD  
Product Manual



100765362, Rev.N  
October 2017

## Document Revision History

Revision	Date	Pages affected and description of change
Rev. A	10/06/2015	Initial release.
Rev. B	10/06/2015	<a href="#">Section 4.4 SMART Attributes</a> revised text.
Rev. C	10/11/2015	Updated the following sections: <a href="#">Section 2.3 Power Consumption</a> , added Note #3: <a href="#">Section 3.2.1 8639 Connector and Pin Descriptions</a> , corrected to reflect 8639 connector.
Rev. D	11/06/2015	Added "Nytro" to product naming throughout the document. Updated the following sections: <a href="#">Section 2.2 Performance</a> Revised performance specs. <a href="#">Section 2.1 Models and Capacity</a> Changed capacity from 1800GB to 1920GB & model # to ST1920HM0001
Rev. E	03/04/2016	Updated the following : <a href="#">Section 1.0 Scope</a> Added 512 to sector size bullet & Added "OoBM (SMBus) Mgmt support" to Interface. <a href="#">Section 2.1 Models and Capacity</a> Title = "Formatted Capacity" & Added 512 Formatted capacities. <a href="#">Section 2.2 Performance</a> Updated Performance Table 2 specs & footnote [1] edited to add - "results are based on lometer and the 4K block sector drive." Table 3 DC noise ripple updates & Table 4 - Added Note 3 Added <a href="#">Section 2.5 Out of Band Management (SMBus)</a> Revised <a href="#">Section 2.5 Out of Band Management (SMBus)</a> , adding Table 5 OBM (SMBus) Protocol; Table 6 <a href="#">Section 2.5.1 Vital Product Data (VDP)</a> Add Note [1] to Table 6 <a href="#">Section 2.6 Environmental Conditions</a> Table 7 - temperature gradient = 30C & Added Humidity to Temperature table, and Table 10 Airflow Units corrected to = LFM <a href="#">Section 3.0 Mechanical Information</a> New Mechanical Drawing & SFF reference note updated to SFF8200 <a href="#">Section 3.2.1 8639 Connector and Pin Descriptions</a> PCIe 8639 Pin Descriptions updated.
Rev. F	June 2016	Updated the following: <a href="#">Section 1.0 Scope</a> , Added Warranty. <a href="#">Section 2.3 Power Consumption</a> . Changed specifications. Revised notes. Added <a href="#">Section 2.5.2 SMBus Electrical Parameters</a> . Reformatted Note, Table, and Bullet template elements to comply with product family documentation:
Rev. G	November 2016	Updated the following: <a href="#">Section 2.1 Models and Capacity</a> <a href="#">Section 2.4 Power Loss Data Protection</a> <a href="#">Section 2.5 Out of Band Management (SMBus)</a> <a href="#">Section 4.3 Log Page Support</a> <a href="#">Section 5.0 Standards</a>
Rev. H	January 2017	Updated <a href="#">Section 5.0 Standards</a> to reflect Class B certification.
Rev. J	January 2017	Updated <a href="#">Section 5.0 Standards</a> to add wording regarding Class B certification.
Rev. K	August 2017	Added <a href="#">Section 2.6.1 Storage</a> under <a href="#">Section 2.6 Environmental Conditions</a> and a note about non-operating temperature in <a href="#">Table 9 Temperature and Humidity on page 9</a> .
Rev. L	September 2017	Updated <a href="#">Section 5.0 Standards</a> . Added new product photo to cover page.
Rev. M	October 2017	Updated <a href="#">Section 5.0 Standards</a> .
Rev. N	October 2017	Updated <a href="#">Section 5.0 Standards</a> .

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# Seagate Technology Support Services

For Nytro Support, visit: <http://www.seagate.com/support/by-product/ssd-and-pcie-flash/>

For information regarding online support and services, visit: <http://www.seagate.com/contacts/>

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## 1.0 Scope

Seagate Nytro XF1440 SSD is a PCIe Gen 3 SSD, designed with the NVMe (Non-Volatile Memory Express) interface that delivers leading performance, low latency, and world class reliability and endurance.

- **Interface:**
  - PCIe Gen 3 x4 - 2.5" NVMe SSD
  - Out of Band Management (SMBus) management support
  - See [Section 2.5, Out of Band Management \(SMBus\)](#).
- **Capacities:**
  - 400GB, 480GB, 800GB, 960GB, 1.6TB, 1.92TB
  - See [Section 2.1, Models and Capacity](#).
- **Components:**
  - eMLC NAND Flash Memory
- **Form Factor:**
  - Industry standard SFF 2.5 inch, 7mm dimensions
- **Power**
  - Lower power than current Enterprise class products (<12.5W)
  - Power Loss Data Protection (PLDP)
  - Hot Plug capable
  - See [Section 2.3, Power Consumption](#) and [Section 2.4, Power Loss Data Protection](#).
- **Shock**
  - Op/Non Op: 1500G @ 0.5ms
  - See [Section 2.6, Environmental Conditions](#).
- **Vibration**
  - Op/Non Op: 3.08 Grms (7-800hz)
  - Op/Non Op: 16.3 Grms (20-2000hz)
  - See [Section 2.6, Environmental Conditions](#).
- **Certifications**
  - CE, BSMI, KCC, C-Tick, FCC, IC, UL, TUV, CB
  - See [Section 5.0 Standards](#).
- **Compliance**
  - RoHS
  - See [Section 5.0 Standards](#).
- **Reliability:**
  - Mean Time Between Failure (MTBF):
  - 2 million hours
  - Data Retention: 3 months @ 40°C
  - Sector Sizes: 4096 and 512 bytes
  - See [Section 2.7, Reliability](#).
- **Endurance**
  - Certain models support up to 3 Drive Writes/day
  - Certain models support up to 0.3 Drive Writes/day
  - See [Section 2.8, Endurance](#).
- **Temperature**
  - Operating: 0 to 70°C (as measured by SMART)
  - Non Operating: -40 to 85°C
  - See [Section 2.6, Environmental Conditions](#).
- **Airflow**
  - See [Section 2.6, Environmental Conditions](#).
- **Performance**
  - Varies by capacity and endurance.
  - See [Section 2.2, Performance](#).
- **Security**
  - Self encryptions available
  - See [Section 5.0 Standards](#).
- **Warranty**
  - 5 years limited

## 2.0 Product Specifications

### 2.1 Models and Capacity

Table 1 Models

Standard Models		SED Models
4096 sector	512 sector	512 sector
ST1920HM0001	ST1920KN0001	ST1920KN0011
ST1600HM0011	ST1600KN0001	ST1600KN0011
ST960HM0001	ST960KN0001	ST960KN0011
ST800HM0021	ST800KN0001	ST800KN0011
ST480HM0001	ST480KN0001	ST480KN0011
ST400HM0021	ST400KN0001	ST400KN0011

Table 2 Formatted Capacity

XF1440 Series	4K LBA Count	512 LBA Count
400GB	97,677,846	781,422,768
480GB	117,212,886	937,703,088
800GB	195,353,046	1,562,824,368
960GB	234,423,126	1,875,385,008
1600GB	390,703,446	3,125,627,568
1920GB	468,843,606	3,750,748,848

### 2.2 Performance

Table 3 Performance

Specification	1.6TB	800GB	400GB	1.92TB	960GB	480GB
Sequential Read (MB/s) 128k, QD=32	2500	2500	2400	2500	2500	2400
Sequential Write (MB/s) 128k, QD=32	900	900	500	900	900	500
Random Read (kIOPS) 4k, QD=64	240	240	220	240	240	220
Random Write (kIOPS) 4k, QD=64	40	33	25	15	12	10
70/30 Mixed Workload Random Read/Write (kIOPS) 4k, QD=64	100	80	55	45	35	25

**NOTE**

Here is more information on Performance:

- **Random Read and Sequential Write:** 400GB and 480GB capacities are limited to 32x 128Gb die active.
- **IOMeter:** Performance results are based on IOMeter. IOMeter is available at <http://sourceforge.net/projects/iometer/>. IOMeter is licensed under the Intel Open Source License and the GNU General Public License.
- **Response times:** Typical response times are measured under nominal conditions of temperature and voltage as measured on a representative sample of drives.
- **Measurements:** Measurements are performed on the drive after the workload reaches steady state, including all background activities required for normal operations.

## 2.3 Power Consumption

The 2.5" drive receives DC power (+12V) through the standard PCIe 8639 interface.

**Table 4 DC Requirements**

Supply Voltage	XF1440 Series
Voltage Tolerances - nominal (%)	12V $\pm$ 10%
DC Ripple/Noise	450mVp-p: 100Hz to 100kHz 250mVp-p: 100kHz to 20MHz 150mVp-p: 20MHz to 80MHz
Rise Time (Max*/Min) *10% ~ 90% Nominal Voltage	100ms* /0s (hot-pluggable)
Fall Time (Min)	100 $\mu$ s @ 1A max discharge
Minimum Off Time	150ms
Inrush Current (Typical Peak)	2A for <2ms

**Table 5 Power**

Specification	XF1440 Series
Max Operating Power (W)	12.5
Power State 1 (W)	8.25
Power State 2 (W)	6.0
Power State 3 (W)	4.5

**NOTE**

Here is more information on Power:

- NVMe Autonomous Power States are not supported.
- Typical power measurements are based on an average of drives tested under nominal conditions.
- Maximum power is defined as RMS over 100ms.

## 2.4 Power Loss Data Protection

The XF1440 implements an energy storage solution called Power Loss Data Protection. This circuit maintains power to the NAND while the NAND is being programmed, even if power to the system is interrupted. Power loss data protection ensures data integrity, and prevents loss of data and the resulting errors reporting back to the host.

## 2.5 Out of Band Management (SMBus)

The XF1440 provides sub-system management data to the host over the SMBus interface at 0x6A. You can find a description of this mechanism in Appendix A of the *NVM Express Management Interface 1.0*.

**Table 6 Out of Band Management (SMBus) Protocol**

Command Code	Offset (byte)	Description																
0	00	<b>Length of Status:</b> Indicates number of additional bytes to read before encountering PEC. This value should always be 6 (06h) in implementations of this version of the spec.																
	01	<p><b>Status Flags (SFLGS):</b> This field indicates the status of the NVM subsystem.</p> <p><b>SMBus Arbitration</b> – Bit 7 is set ‘1’ after a SMBus block read is completed all the way to the stop bit without bus contention and cleared to ‘0’ if a SMBus Send Byte FFh is received on this SMBus slave address.</p> <p><b>Drive Not Ready</b> – Bit 6 is set to ‘1’ when the subsystem cannot process NVMe management commands, and the rest of the transmission may be invalid. If cleared to ‘0’, then the NVM subsystem is fully powered and ready to respond to management commands. This logic level intentionally identifies and prioritizes powered up and ready drives over their powered off neighbors on the same SMBus segment.</p> <p><b>Drive Functional</b> – Bit 5 is set to ‘1’ to indicate an NVM subsystem is functional. If cleared to ‘0’, then there is an unrecoverable failure in the NVM subsystem and the rest of the transmission may be invalid.</p> <p><b>Reset Not Required</b> - Bit 4 is set to ‘1’ to indicate the NVM subsystem does not need a reset to resume normal operation. If cleared to ‘0’ then the NVM subsystem has experienced an error that prevents continued normal operation. A controller reset is required to resume normal operation.</p> <p><b>Port 0 PCIe Link Active</b> - Bit 3 is set to ‘1’ to indicate the first port’s PCIe link is up (i.e., the Data Link Control and Management State Machine is in the DL_Active state). If cleared to ‘0’, then the PCIe link is down.</p> <p><b>Port 1 PCIe Link Active</b> - Bit 2 is set to ‘1’ to indicate the second port’s PCIe link is up. If cleared to ‘0’, then the second port’s PCIe link is down or not present.</p> <p>Bits 1-0 shall be set to ‘1’.</p>																
	02	<p><b>SMART Warnings:</b> This field shall contain the Critical Warning field (byte 0) of the NVMe SMART / Health Information log. Each bit in this field shall be inverted from the NVMe definition (i.e., the management interface shall indicate a ‘0’ value while the corresponding bit is ‘1’ in the log page). See the NVMe specification for bit definitions.</p> <p>If there are multiple controllers in the NVM subsystem, the management endpoint shall combine the Critical Warning field from every controller such that a bit in this field is: Cleared to ‘0’ if any controller in the subsystem indicates a critical warning for that corresponding bit. Set to ‘1’ if all controllers in the NVM subsystem do not indicate a critical warning for the corresponding bit.</p>																
	03	<p><b>Composite Temperature (CTemp):</b> This field indicates the current temperature in degrees Celsius. If a temperature value is reported, it should be the same temperature as the Composite Temperature from the SMART log of hottest controller in the NVM subsystem. The reported temperature range is vendor specific, and shall not exceed the range -60 to +127°C. The 8 bit format of the data is shown below.</p> <p>This field should not report a temperature when that is older than 5 seconds. If recent data is not available, the NVMe management endpoint should indicate a value of 80h for this field.</p> <table border="1"> <thead> <tr> <th>Value</th> <th>Description</th> </tr> </thead> <tbody> <tr> <td>00h-7Eh</td> <td>Temperature is measured in degrees Celsius (0 to 126C)</td> </tr> <tr> <td>7Fh</td> <td>127C or higher</td> </tr> <tr> <td>80h</td> <td>No temperature data or temperature data is more the 5 seconds old.</td> </tr> <tr> <td>81h</td> <td>Temperature sensor failure</td> </tr> <tr> <td>82h-C3h</td> <td>Reserved</td> </tr> <tr> <td>C4</td> <td>Temperature is -60C or lower</td> </tr> <tr> <td>C5-FFh</td> <td>Temperature measured in degrees Celsius is represented in twos complement (-1 to -59C)</td> </tr> </tbody> </table>	Value	Description	00h-7Eh	Temperature is measured in degrees Celsius (0 to 126C)	7Fh	127C or higher	80h	No temperature data or temperature data is more the 5 seconds old.	81h	Temperature sensor failure	82h-C3h	Reserved	C4	Temperature is -60C or lower	C5-FFh	Temperature measured in degrees Celsius is represented in twos complement (-1 to -59C)
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04	<p><b>Percentage Drive Life Used (PDLU):</b> Contains a vendor specific estimate of the percentage of NVM subsystem NVM life used based on the actual usage and the manufacturer’s prediction of NVM life. If an NVM subsystem has multiple controllers the highest value is returned. A value of 100 indicates that the estimated endurance of the NVM in the NVM subsystem has been consumed, but may not indicate an NVM subsystem failure. The value is allowed to exceed 100. Percentages greater than 254 shall be represented as 255. This value should be updated once per power-on hour and equal the Percentage Used value in the NVMe SMART Health Log Page.</p>																	
06 : 05	<b>Reserved:</b> Shall be set to 0000h.																	
07	<b>PEC:</b> An 8 bit CRC calculated over the slave address, command code, second slave address and returned data. Algorithm is in SMBus Specifications.																	



**Table 6 Out of Band Management (SMBus) Protocol (continued)**

Command Code	Offset (byte)	Description
8	08	<b>Length of identification:</b> Indicates number of additional bytes to read before encountering PEC. This value should always be 22 (16h) in implementations of this version of the spec.
	10 : 09	<b>Vendor ID:</b> The 2 byte vendor ID, assigned by the PCI SIG. Should match VID in the Identify Controller command response. MSB is transmitted first.
	30 : 11	<b>Serial Number:</b> 20 characters that match the serial number in the NVMe Identify Controller command response. First character is transmitted first.
	31	<b>PEC:</b> An 8 bit CRC calculated over the slave address, command code, second slave address and returned data. Algorithm is in SMBus Specifications.
32+	255 : 32	Vendor Specific: This data structure shall not exceed the maximum read length of 255 specified in the SMBus version 3 specification. Preferably length is not greater than 32 for compatibility with SMBus 2.0, additional blocks shall be on 8 byte boundaries.

### 2.5.1 Vital Product Data (VDP)

XF1440 accesses a Vital Product Data (VPD) EEPROM page as listed below through address 0xA6. This requires 3.3V Auxiliary voltage.

**Table 7 VDP Structure**

Address	Function	Type	Size (B)	Default Size	Description
0	Class Code	RO	3	Vendor	Device type and programming interface
3	ID	RO	2	Vendor	PCI-SIG Vendor ID
5			20	Vendor	Serial Number (vendor unique)
25			40	Vendor	Model Number (ASCII string)
65	PCIe Port 0 Capabilities	RO	2	Vendor	Maximum Link Speed
66					Maximum Link Width
67	PCIe Port 1 Capabilities	RO	2	Vendor	Maximum Link Speed
68					Maximum Link Width
69	Initial Power Requirements	RO	3	Vendor	12V power rail initial power requirement (W)
70				0	Reserved
71				0	Reserved
72	Maximum Power Requirements	RO	3	Vendor	12V power rail initial power requirement (W)
73				0	Reserved
74				0	Reserved
75	Capability List Pointer	RO	2	Vendor	16-bit address pointer to start of capability list (zero means no capability list)

**NOTE** Initial and Maximum Power requirements are not supported.

## 2.5.2 SMBus Electrical Parameters

The SMBus interface operates only when 3.3V\_AUX is supplied to the drive. When 3.3V\_AUX and 12V are supplied to the drive, the SMBus interface functions fully. When only 3.3V\_AUX is supplied to the drive (12V off), VPD data remains accessible over the SMBus interface, but other functions are unavailable. No specific sequencing is needed for the 12V and 3.3V\_AUX input voltages.

**Table 8 SMBus Electrical Parameters**

Specification		XF1440 Series
3.3V Auxiliary Voltage Supply		2.8V - 3.8V
3.3V Auxiliary Maximum Continuous Current		
SMBus Idle		20µA
SMBus Active		1mA
3.3V Auxiliary Maximum Capacitive Load		5µF

## 2.6 Environmental Conditions

**Table 9 Temperature and Humidity**

Specification		XF1440 Series
Temperature (°C)	Operating (as measured by SMART)	0 to 70
	Non-Operating	-40 to 85 <sup>1</sup>
Temperature Gradient Maximum	Operating	30°C/hr
	Non-Operating	30°C/hr
Humidity	Operating	5%-95%
	Non-Operating	5%-95%

**NOTE** 1. Limited to shelf life while product is still in the shipping package.

### 2.6.1 Storage

You can store the drive for a maximum of 180 days in the original unopened Seagate shipping package or 60 days, unpackaged, in the defined non-operating limits (See [Table 9, Temperature and Humidity](#)). You can extend storage to 1 year packaged or unpackaged under optimal environmental conditions (<40°C, <40% relative humidity non-condensing, and non-corrosive environment).

**Table 10 Shock**

Specification		XF1440 Series
Shock - Maximum	Operating / Non Operating	1500 G at 0.5 ms

**NOTE** Specification does not cover connection issues that might result from testing at this level.

- **Operating shock:** The drive, as installed for normal operation, operates error free while subjected to intermittent shock not exceeding the specification. Shock may be applied in the X, Y, or Z-axis. Shock is not to be repeated more than once every 2 seconds.
- **Non-Operating shock:** The limits of non-operating shock apply to all conditions of handling and transportation. This includes isolated drive and integrated drives. Shock may be applied in the X, Y, or Z-axis.

**Table 11 Vibration**

Specification		XF1440 Series
Vibration - Profile	Operating	3.08 Grms (7-800 Hz),
	Non Operating	16.3 Grms (20-2000 Hz)

**NOTE**

Here is more information on Vibration:

- **Operating vibration:** The drive, as installed for normal operation, shall operate error free while subjected to specified vibration not exceeding specification. Vibration may be applied in the X, Y, or Z-axis.
- **Non-Operating vibration:** The limits of non-operating vibration shall apply to all conditions of handling and transportation. This includes both isolated drive and integrated drives. Vibration may be applied in the X, Y, or Z-axis.

**Table 12 Airflow Requirements for SFF**

Airflow Definition	Unit	Ambient Temperature	400GB/480GB	800GB/960GB	1600GB/1920GB
Airflow Along Drive	LFM	35°C	110	412	412

**NOTE**

It is recommended that airflow for 2.5-inch form factor should be towards the server, from the non-connector side to the connector side. Airflow is specified across the surface of the drive. Spacing all sides is assumed to be 3mm.

## 2.7 Reliability

**Table 13 Reliability**

Specification	XF1440 Series
Mean Time Between Failures (MTBF)	2 million hours
Data Retention	3 months @ 40°C

**NOTE**

The MTBF specification is based on these assumptions for Enterprise Storage System environments: 8760 power on hours per year, 250 power on/off cycles per year, and nominal voltages.

The drive achieves specified MTBF when operating in an environment that ensures the case temperatures do not exceed the temperature specifications.

Data Retention is the time that NAND retains data at maximum rated endurance

## 2.8 Endurance

**Table 14 Endurance**

2.5"	Model Type	400GB	480GB	800GB	960GB	1600GB	1920GB
Endurance - Drive Writes per Day	High Endurance	3		3		3	
	High Capacity		0.3		0.3		0.3

**NOTE**

Endurance rating is the expected amount of host data that can be written by product when subjected to a specified workload at a specified operating and storage temperature over the specified product life. For the specific workload to achieve this level of endurance, *please refer to JEDEC Specification JESD218*. Terabyte Writes is defined as 1x10<sup>12</sup> Bytes.

### 3.0 Mechanical Information

#### 3.1 Mechanical Dimensions and Weight

Weight: 2.5" models 0.198 pounds 90 grams

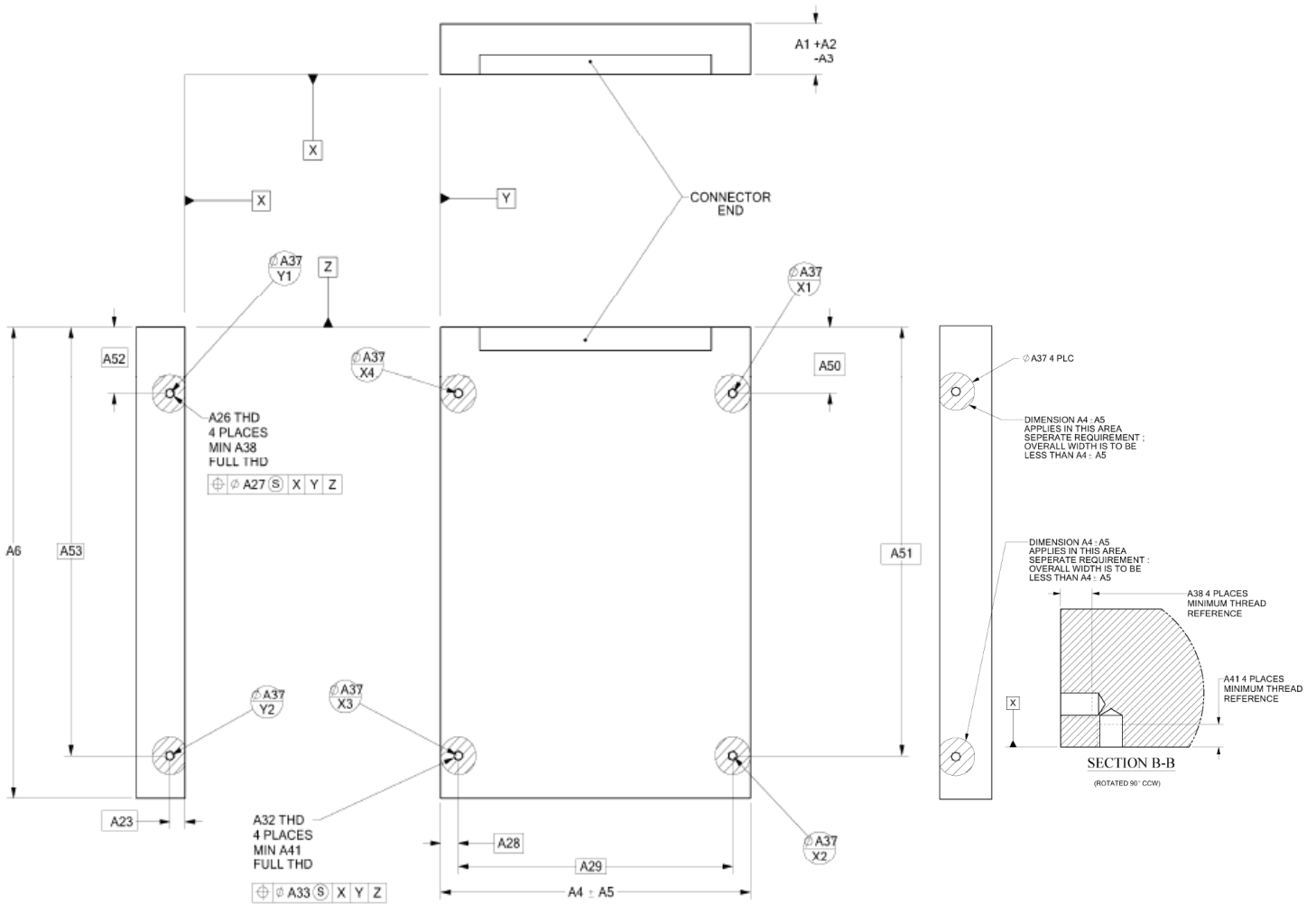


Figure 1 Configuration dimensions (2.5" models)

**NOTE** These dimensions conform to the Small Form Factor Standard documented in SFF-8200 and SFF-8639. The latest revisions may be found at:

<http://www.snia.org/sff/specifications>.

#### 3.2 Bottom Cover Stiffness/Deflection

Table 15 Bottom Cover Stiffness/Deflection

Operating: No uncorrectable errors	10mm probe: 1.02kgf or 5mm probe: 0.92kgf
Non-Operating: No uncorrectable errors	20mm probe: 2.0kgf on any point on bottom cover

### 3.2.1 8639 Connector and Pin Descriptions

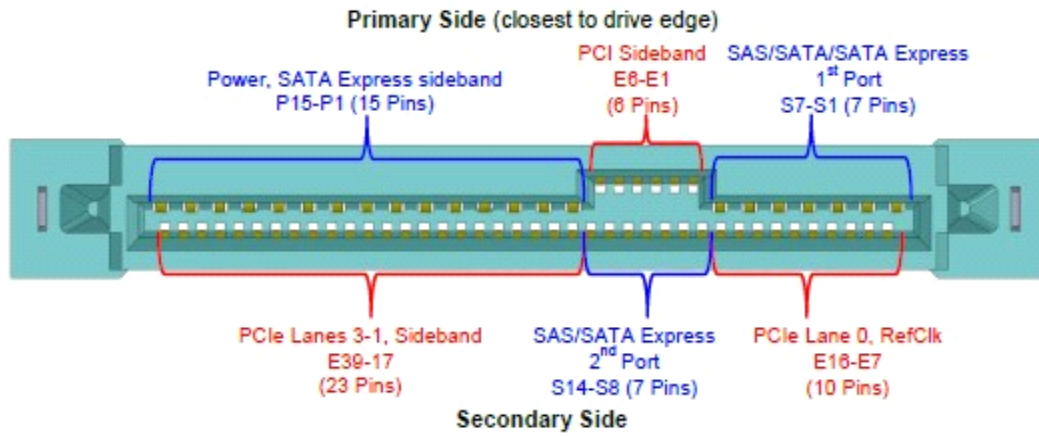


Figure 2 8639 Connector

**NOTE**

To see the latest specification for the physical 8639 connector, refer to [www.pcisig.com](http://www.pcisig.com) website and the latest PCI Express Electromechanical specification.

Pin	Name	Description	Pin	Name	Description
S1	GND	Ground	E7	REFCLK0	Reference clock port 0
S2	NU	Not used (SATA/SAS)	E8	REFCLK0-	Reference clock port 0
S3	NU	Not used (SATA/SAS)	E9	GND	Ground
S4	GND	Ground	E10	PETp0	Transmitter differential pair, Lane
S5	NU	Not used (SATA/SAS)	E11	PETn0	Transmitter differential pair, Lane
S6	NU	Not used (SATA/SAS)	E12	GND	Ground
S7	GND	Ground	E13	PERn0	Receiver differential pair, Lane 0
E1	NU	(not used)	E14	PERp0	Receiver differential pair, Lane 0
E2	NU	(not used)	E15	GND	Ground
E3	NU	3.3V auxiliary power (required for	E16	RSVD	Reserved
E4	NU	(not used)	S8	GND	Ground
E5	PERST0#	Fundamental reset port 0	S9	NU	Not used (SATA&SAS)
E6	RSVD	Reserved (Seagate Internal)	S10	NU	Not used (SATA&SAS)
P1	NU	Not used (SATA&SAS)	S11	GND	Ground
P2	NU	Not used (SATA&SAS)	S12	NU	Not used (SATA&SAS)
P3	CLKREQ#	Clock Request	S13	NU	Not used (SATA&SAS)
P4	IfDet#	Interface detect (drive type)	S14	GND	Ground
P5	GND	Ground	S15	RSVD	Reserved (Seagate internal)
P6	GND	Ground	S16	GND	Ground
P7	NU	Not used (SATA/SAS)	S17	PETp1	Transmitter differential pair, Lane
P8	NU	Not used (SATA/SAS)	S18	PETn1	Transmitter differential pair, Lane
P9	NU	Not used (SATA/SAS)	S19	GND	Ground
P10	PRSNT#	Presence detect (also used for drive type)	S20	PERn1	Receiver differential pair, Lane 1
P11	ACT	Activity signal from the drive	S21	PERp1	Receiver differential pair, Lane 1
P12	Hot-Plug	Ground	S22	GND	Ground
P13	+12V_pre	12V power	S23	PETp2	Transmitter differential pair, Lane
P14	+12V	12V power	S24	PETn2	Transmitter differential pair, Lane
P15	+12V	12V power	S25	GND	Ground
			S26	PERn2	Receiver differential pair, Lane 2
			S27	PERp2	Receiver differential pair, Lane 2
			S28	GND	Ground
			E17	PETp3	Transmitter differential pair, Lane
			E18	PETn3	Transmitter differential pair, Lane
			E19	GND	Ground
			E20	PERn3	Receiver differential pair, Lane 3
			E21	PERp3	Receiver differential pair, Lane 3
			E22	GND	Ground
			E23	NU	SMBus clock (available if
			E24	NU	SMBus data (available if
			E25	NU	Dual port enable (not used)

**Figure 3 PCIe 8639 Pin Descriptions**

## 4.0 Interface requirements

### 4.1 PCIe features

The Seagate Nytro SSD supports NVMe spec 1.2b. Below is a table showing the supported Features, Op-code, and whether vendor specific, mandatory, or optional.

**Table 16 PCIe Features**

Feature ID	M/O	Description	Supported
01h	M	Arbitration	Yes
02h	M	Power Management	Yes
03h	O	LBA Range Type	No
04h	M	Temperature Threshold	Yes
05h	M	(Time limited) Error Recovery	Yes
06h	O	Volatile Write Cache	No
07h	M	Number of Queues	Yes
08h	M	Interrupt Coalescing	Yes
09h	M	Interrupt Vector Configuration	Yes
0Ah	O	Write Atomicity	No
0Bh	M	Asynchronous Event Configuration	Yes
0Ch	O	Autonomous Power State Transition	No
0Dh	O	Host Memory Buffer	No
80h	O	Software Progress Marker	No
81h	O	Host Identifier	No
82h	O	Reservation Notification Mask	No
83h	O	Reservation Persistence	No
C0h	VS	System Time	Yes
C1h	VS	Test Unit Ready	Yes
C2h	VS	Media Life Left Threshold	Yes

### 4.2 Interface Commands Supported:

The Seagate Nytro SSD supports all the mandatory NVMe Admin and I/O command-sets in *NVMe spec 1.2b*. In addition, several optional commands are also supported. Below are tables showing the Commands, Op-code, whether Admin or IO and mandatory or optional:

**Table 17 Supported I/O Commands**

Feature ID	M/O	Command	Supported
00h	M	Flush	Yes
01h	M	Write	Yes
02h	M	Read	Yes
04h	O	Write Uncorrectable	Yes
05h	O	Compare	No
08h	O	Write Zones	Yes
09h	O	Dataset Management - Trim	Yes
		Dataset Management - IDW	No
		Dataset Management - IDR	No

**Table 17 Supported I/O Commands (continued)**

Feature ID	M/O	Command	Supported
0Dh	O	Reservation Register	No
0Eh	O	Reservation Report	No
11h	O	Reservation Acquire	No
12h	O	Reservation Release	No

**Table 18 Supported Admin Commands**

Op-code	M/O	Command	Supported
00h	M	Delete I/O SQ	Yes
01h	M	Create I/O SQ	Yes
02h	M	Get log Page	Yes
04h	M	Delete I/O CQ	Yes
05h	M	Create I/O CQ	Yes
06h	M	Identify	Yes
08h	M	Abort	Yes
09h	M	Set Features	Yes
0Ah	M	Get Features	Yes
0Ch	M	Async Event Request	Yes
0Dh	O	Namespace Management	No
10h	M	Firmware Commit	Yes
11h	M	Firmware Image Download	Yes
15h	O	Namespace Attachment	No
80h	O	Format NVM	Yes
81h	O	Security Send	Yes
82h	O	Security Receive	Yes
C0h	VS	Diagnostic Send	Yes
C1h	VS	Diagnostic Receive	Yes

### 4.3 Log Page Support

The Seagate Nytro SSD supports the following mandatory log pages defined in NVMe 1.2b specification.

**Table 19 Log Page Support**

Log Page	M/O	Description	Supported
01h	M	Error Information	Yes
02h	M	SMART/Health Information	Yes
03h	M	Firmware Slot Information	Yes
05h	O	Commands Supported and Effects Log	Yes
C4h	VS	Extended SMART Attributes	Yes
C5h	VS	List of Supported Log Pages	Yes
C8h	VS	Recent history Log Page	Yes
CBh	VS	PCIe Error Counter Log	Yes



## 4.4 SMART Attributes

The following table lists the supported SMART attributes.

**Table 20 SMART Attributes (Log Identifier 02h)**

Byte	# of Bytes	Attribute	Description
0	1	<b>Critical Warning:</b> These bits, if set, flag various warning sources. Bit 0: Available Spare is below Threshold Bit 1: Temperature has exceeded Threshold Bit 2: Reliability is degraded due to excessive media or internal errors Bit 3: Media is placed in Read- Only Mode Bit 4: Volatile Memory Backup System has failed (e.g., enhanced power loss capacitor test failure) Bits 5-7: Reserved	Any of the critical warning can be tied to asynchronous event notification. Drive Health Indicator defined under bytes 3095-3076 of Identify Controller may still indicate "healthy" status when the critical warning flag is set.
1	2	Temperature: Overall Device current temperature in Kelvin	For AIC, this reports the NAND temperature, for 2.5-inch FF, this reports the case temperature,
3	1	Available Spare: Contains a normalized percentage (0 to 100%) of the remaining spare capacity available	Starts from 100 and decrements.
4	1	Available Spare Threshold	Threshold is set to 10%.
5	1	Percentage Used Estimate (Value allowed to exceed 100%)	A value of 100 indicates that the estimated endurance of the device has been consumed, but may not indicate a device failure. The value is allowed to exceed 100. Percentages greater than 254 shall be represented as 255. This value shall be updated once per power-on hour (when the controller is not in a sleep state).
32	16	Data Units Read (in LBAs)	Contains the number of 512 byte data units the host has read from the controller; this value does not include metadata. This value is reported in thousands (i.e., a value of 1 corresponds to 1000 units of 512 bytes read) and is rounded up. When the LBA size is a value other than 512 bytes, the controller shall convert the amount of data read to 512-byte units.
48	16	Data Units Write (in LBAs)	Contains the number of 512 byte data units the host has written to the controller; this value does not include metadata. This value is reported in thousands (i.e., a value of 1 corresponds to 1000 units of 512 bytes written) and is rounded up. When the LBA size is a value other than 512 bytes, the controller shall convert the amount of data written to 512-byte units. For the NVM* command set, logical blocks written as part of Write operations shall be included in this value. Write Uncorrectable commands shall not impact this value.
64	16	Host Read Commands	Contains the number of read commands issued to the controller.
80	16	Host Write Commands	Contains the number of write commands issued to the controller.

**Table 20 SMART Attributes (Log Identifier 02h) (continued)**

Byte	# of Bytes	Attribute	Description
96	16	Controller Busy Time (in minutes)	Contains the amount of time the controller is busy with I/O commands. The controller is busy when there is a command outstanding to an I/O Queue (specifically, a command was issued by way of an I/O Submission Queue Tail doorbell write and the corresponding completion queue entry has not been posted yet to the associated I/O Completion Queue). This value is reported in minutes.
112	16	Power Cycles	Contains the number of power cycles.
128	16	Power On Hours	Contains the number of power-on hours. This does not include time that the controller was powered and in a low power state condition.
144	16	Unsafe Shutdowns	Contains the number of unsafe shutdowns. This count is incremented when a shutdown notification (CC.SHN) is not received prior to loss of power.
160	16	Media Errors	Contains the number of occurrences where the controller detected an unrecovered data integrity error. Errors such as uncorrectable ECC, CRC checksum failure, or LBA tag mismatch are included in this field.
176	16	Number of Error Information Log Entries	Contains the number of Error Information log entries over the life of the controller.

## 5.0 Standards

### 5.1 Agency and Safety Certifications

Each Hard Drive and Solid State Drive ("drives") has a product label that includes certifications that are applicable to that specific drive. The following information provides an overview of requirements that may be applicable to the drive.

#### 5.1.1 Safety certification

These products are certified to meet the requirements of UL/cUL 60950-1, EN 60950-1, and may also include, IEC 62368, UL 62368 and EN 62368.

#### 5.1.2 European Union (EU) CE Marking Requirements

Drives that display the CE mark comply with the European Union (EU) requirements specified in the Electromagnetic Compatibility Directive (2014/30/EU) put into force on 20 April 2016. Testing is performed to the levels specified by the product standards for Information Technology Equipment (ITE). Emission levels are defined by EN 55032:2012, Class B and the immunity levels are defined by EN 55024:2010.

The drives also meet the requirements of The Low Voltage Directive (LVD) 2014/35/EU.

Seagate drives are tested in representative end-user systems. Although CE-marked Seagate drives comply with all relevant regulatory requirements and standards for the drives, Seagate cannot guarantee that all system-level products into which the drives are installed comply with all regulatory requirements and standards applicable to the system-level products. The drive is designed for operation inside a properly designed system (e.g., enclosure designed for the drive), with properly shielded I/O cable (if necessary) and terminators on all unused I/O ports. Computer manufacturers and system integrators should confirm EMC compliance and provide CE marking for the system-level products.

For compliance with the RoHS "Recast" Directive 2011/65/EU (RoHS 2), see [Section 5.2.1.1, Restriction of Hazardous Substances in Electrical and Electronic Equipment](#).

#### 5.1.3 Australian RCM Compliance Mark

If these models have the RCM marking, they comply with the Australia/New Zealand Standard AS/NZ CISPR32 and meet the Electromagnetic Compatibility (EMC) Framework requirements of the Australian Communication and Media Authority (ACMA).

#### 5.1.4 Canada ICES-003

If this model has the ICES-003:2016 marking it complies with requirements of ICES tested per ANSI C63.4-2014.

#### 5.1.5 South Korean KC Certification Mark

The South Korean KC Certification Mark means the drives comply with paragraph 1 of Article 11 of the Electromagnetic Compatibility control Regulation and meet the Electromagnetic Compatibility (EMC) Framework requirements of the Radio Research Agency (RRA) Communications Commission, Republic of Korea. These drives have been tested and comply with the Electromagnetic Interference/Electromagnetic Susceptibility (EMI/EMS) for Class B products. Drives are tested in a representative, end-user system by a Korean-recognized lab.

기종별	사용자안내문
B급 기기 (가정용 방송통신기자재)	이 기기는 가정용(B급) 전자파적합기기로서 주로 가정에서 사용하는 것을 목적으로 하며, 모든 지역에서 사용할 수 있습니다.

## 5.1.6 Morocco Commodity Mark

Seagate drives are tested for compliance and complies with the European Union (EU) Electromagnetic Compatibility (EMC) Directive 2014/30/EU and the Low Voltage Directive (LVD) 2014/35/EU. Accordingly, the drives also meets the requirements of Morocco's Order of the Minister of Industry, Trade, Investment and Digital Economy No. 2574-14 of 29 Ramadan 1436 (16 July 2015) on electromagnetic compatibility of equipment.

For drives with the Morocco Mark, Seagate has added the Moroccan Commodity Mark to the drives provided to the OEM for the sale of Customer Kits produced by our OEM customers that are intended to be incorporated into the OEM's finished system-level product by an end user. The Customer Kits are considered 'devices' under Morocco's Order of the Minister of Industry, Trade, Investment and Digital Economy No. 2574-14 of 29 Ramadan 1436 (16 July 2015) on electromagnetic compatibility of equipment.

## 5.1.7 Taiwanese BSMI

Drives with the Taiwanese certification mark comply with Chinese National Standard, CNS13438.

For compliance with the Taiwan Bureau of Standards, Metrology and Inspection's (BSMI) requirements, see [Section 5.2.3, Taiwan Requirements — Taiwan RoHS](#).

## 5.1.8 FCC verification

These drives are intended to be contained solely within a personal computer or similar enclosure (not attached as an external device). As such, each drive is considered to be a subassembly even when it is individually marketed to the customer. As a subassembly, no Federal Communications Commission verification or certification of the device is required.

Seagate has tested this device in enclosures as described above to ensure that the total assembly (enclosure, disk drive, motherboard, power supply, etc.) does comply with the limits for a Class B computing device, pursuant to Subpart J, Part 15 of the FCC rules. Operation with noncertified assemblies is likely to result in interference to radio and television reception.

**Radio and television interference.** This equipment generates and uses radio frequency energy and if not installed and used in strict accordance with the manufacturer's instructions, may cause interference to radio and television reception.

This equipment is designed to provide reasonable protection against such interference in a residential installation. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause interference to radio or television, which can be determined by turning the equipment on and off, users are encouraged to try one or more of the following corrective measures:

- Reorient the receiving antenna.
- Move the device to one side or the other of the radio or TV.
- Move the device farther away from the radio or TV.
- Plug the computer into a different outlet so that the receiver and computer are on different branch outlets.

If necessary, users should consult a dealer or an experienced radio/television technician for additional suggestions. Users may find helpful the following booklet prepared by the Federal Communications Commission: *How to Identify and Resolve Radio-Television Interference Problems*. This booklet is available from the Superintendent of Documents, U.S. Government Printing Office, Washington, DC 20402. Refer to publication number 004-000-00345-4.

## 5.2 Environmental protection

Seagate designs its products to meet environmental protection requirements worldwide, including regulations restricting certain chemical substances.

## 5.2.1 European Union Restriction of Hazardous Substance Law

### 5.2.1.1 Restriction of Hazardous Substances in Electrical and Electronic Equipment

Seagate drives are designed to be compliant with the European Union RoHS "Recast" Directive 2011/65/EU (RoHS 2) as amended by Directive (EU) 2015/863. The RoHS2 restricts the use of certain hazardous substances such as Lead, Cadmium, Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB) and Polybrominated Diphenyl Ether (PBDE), BisBis(2-Ethylhexyl) phthalate (DEHP), Benzyl butyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) in electrical and electronic equipment (EEE).

### 5.2.1.2 Substances of Very High Concern (SVHC)

The European Union REACH (Registration, Evaluation, Authorization and Restriction of Chemicals) Regulation (EC) 1907/2006 regulates chemicals shipped into and used in Europe. A number of parts and materials in Seagate products are procured from external suppliers. We rely on the representations of our suppliers regarding the presence of REACH substances in these articles and materials. Our supplier contracts require compliance with our chemical substance restrictions, and our suppliers document their compliance with our requirements by providing full-disclosure material content declarations that disclose inclusion of any REACH-regulated substance in such articles or materials. Product-specific REACH declarations are available upon request through your Seagate Sales Representative.

## 5.2.2 China Requirements —China RoHS 2



China RoHS 2 refers to the Ministry of Industry and Information Technology Order No. 32, effective July 1, 2016, titled Management Methods for the Restriction of the Use of Hazardous Substances in Electrical and Electronic Products. To comply with China RoHS 2, Seagate determines this product's Environmental Protection Use Period (EPUP) to be 20 years in accordance with the *Marking for the Restricted Use of Hazardous Substances in Electronic and Electrical Products*, SJ/T 11364-2014.

**Table 21 China - Hazardous Substances**

部件名称 Part Name	有害物质 Hazardous Substances					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr <sup>+6</sup> )	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
印刷电路板组装 PCBA	X	O	O	O	O	O
机壳 Chassis	X	O	O	O	O	O

本表格依据 SJ/T 11364 的规定编制。

This table is prepared in accordance with the provisions of SJ/T 11364-2014

O: 表示该有害物质在该部件所有均质材料中的含量均在 GB/T 26572 规定的限量要求以下。

O: Indicates that the hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement of GB/T26572.

X: 表示该有害物质至少在该部件的某一均质材料中的含量超出 GB/T 26572 规定的限量要求。

X: Indicates that the hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement of GB/T26572.

### 5.2.3 Taiwan Requirements — Taiwan RoHS

Taiwan RoHS refers to the Taiwan Bureau of Standards, Metrology and Inspection's (BSMI) requirements in standard CNS 15663, Guidance to reduction of the restricted chemical substances in electrical and electronic equipment. Seagate products must comply with the "Marking of presence" requirements in Section 5 of CNS 15663, effective January 1, 2018. This product is Taiwan RoHS compliant.

The following table meets the Section 5 "Marking of presence" requirements.

**Table 22 Taiwan - Restricted Substances**

設備名稱：硬盤設備 /SSD，型號：僅適用於內部使用 Equipment Name: Hard Disk Device/SSD, Type Designation: Internal Use Only						
單元 Unit	限用物質及其化學符號 Restricted Substance and its chemical symbol					
	鉛 (Pb)	汞 (Hg)	鎘 (Cd)	六價鉻 (Cr <sup>+6</sup> )	多溴聯苯 (PBB)	多溴二苯醚 (PBDE)
印刷电路板組裝 PCBA	—	0	0	0	0	0
機殼 Chassis	—	0	0	0	0	0
備考 1. "0" 係指該項限用物質之百分比含量未超出百分比含量基準值。 Note 1. "0" indicates that the percentage content of the restricted substance does not exceed the percentage of reference value of presence. 備考 2. "—" 係指該項限用物質為排除項目。 Note 2. "—" indicates that the restricted substance corresponds to the exemption.						

## 6.0 Reference Documents

In case of conflict between this document and any referenced document, this document takes precedence.

**Table 23 Reference Documents**

Title	Location
PCIe specifications:  PCIe - PCI Express Electromechanical specification, revision 3.0  NVMe - Non Volatile Memory Express specification 1.2b  PCIe CEM - PCI Express Card Electromechanical specification, revision 1.1	<a href="http://www.pcisig.com">www.pcisig.com</a>  <a href="http://www.nvmexpress.org">www.nvmexpress.org</a>
Trusted Computing Group (TCG) Documents  TCG Storage Architecture Core Specification, Rev. 1.0  Storage Work Group Security Subsystem Class: Opal, Version 2.00"	<a href="http://www.trustedcomputinggroup.org">www.trustedcomputinggroup.org</a>
Solid State Drive Requirements and Endurance Test Methods  JESD218  JESD219	<a href="http://www.jedec.org">www.jedec.org</a>



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